	∠QDE	CIFICAT	ION>	
	\0FL			DIQ-SPE-150(00)
				g.22,2022
To:				
•	CUSTOM	ER'S PRODUCT NA	ME	
	COSTOM	EN 3 FRODUCT NA	NVIC .	
	ASDI PRO	DDUCT NAME:		
	SIPM100	03A-SERIES		
			ı	
RECEIPT CONFIRM	IATION			
UNCOND	ITIONAL CONSENT		CONDITIONAL CO	DNSENT
	APPROVED		CHECKED	
		•		
ASDI SIGNATURE				
	APPROVED	CHECKED	PREPARED	
	Xianglong Li	Liang Wang	Jiayin Cai	



REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Aug.22,2022	New release	Xianglong Li	Liang Wang	Jiayin Cai

CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

CAUTION

*The product should be used within 12 monthes.

Focus on the storage conditions.

Solderability may become weak if it exceeds the period.

*Do not use and store the product in condition of gas corrosion (Salt,Acid,Alkaline).

*The products must be preheated before soldering.

The operating temperature including self-generated heat must be within '-55~+125℃

*Rework by soldering iron; Please keep the mentioned conditions in this specification.

*In case of insert P.C. Board on chassis, do not add mechanical stress to the product.

*Be careful to arrange of non-magnetic field type inductors.

The error may be caused by magnetic field coupling.

*In case handle the products, please use wrist strap for ground static discharge on human body.

The product keeps away from magnet or magnetized things.

*Do not use the product beyond the mentioned conditions in this specification.

*About an application

The products listed on this specification sheet are intended for use in general electronic equipment

(AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

*The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

1)Aerospace/Aviation equipment
2)Military equipment
3)Seabed equipment
4)Safety equipment
5)Medical equipment
9)Other applications that are not

considered general-purpose applications

If you intend to use the products in the following applications, please contact our sales office.

Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment

When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

Xiamen ASDI Electronics Co.,Ltd.	DWG.No. ASDIQ-SPE-150(00)	ISSUE	
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CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
	SIPM1003A-SERIES	

1.Applications

Note PC power system, incl. IMVP-6, Switch and servers,Base stations Battery powered devices,SSD modules,DC/DC converter .

2.INDEX

Listed item	Attachment&Tables	Page
1.Features	Please see (1)	3/7
2.Dimensions	Please see (2)	3/7
3.Recommend Land Pattern	Please see (3)	3/7
4.Part Numbering	Please see (4)	3/7
5.Electrical Specifications	Please see (5)	3/7
6.Structure and Components	Please see (6)	4/7
7.Reliability Tests	Please see (7)	4/7
8. Soldering and Mounting	Please see (8)	5/7
9.Packaging Information	Please see (9)	5/7
10.Note	Please see (10)	7/7

3.Manufacturing Location

China

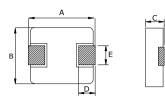
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- (1)Features
 ROHS, Halogen Free and REACH compliance
 High rated current
 125°C maximum total temperature operation
 11.5×10.3×3.0mm maximum surface mount package

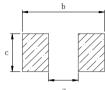
 - ·Ultra low buzz noise due to molding construction

(2)Dimensions



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SIPM1003A	11.5MAX	10.0±0.3	2.8±0.2	2.0±0.5	3.0±0.5

(3)Recommend Land Pattern



		a
a typ	b typ	c typ
5.4	13.6	4.1

Marking
The inductor is marked with a 3-digit code

Nominal Inductance			
Example	Nominal Value		
1R0	1.0 µH		
100	10 μH		
101	100 µH		

Note: Using Ink for marking



(4)Part Numbering

SIPM 1003 1R5 Α

- A: Series B: Dimension C: Material

- D: Inductance E: Inductance Tolerance
- 1R5=1.5µH M=±20%

(5)Electrical Specifications

	Inductance	DC Resistance	Saturation Current	Heating Rating Current
ASDI Part Number	L0(μH)	DCR (mΩ)	I sat(A)	Irms (A)
	±20% 100 kHz/1V	MAX	TYP.	TYP.
SIPM1003A-R22M	0.22	1.2	50	33
SIPM1003A-R33M	0.33	1.6	32	23
SIPM1003A-R36M	0.36	1.6	28	23
SIPM1003A-R47M	0.47	2.5	26	22
SIPM1003A-1R0M	1.00	6.0	21	15
SIPM1003A-2R2M	2.20	9.0	14	11
SIPM1003A-3R3M	3.30	16.0	12	9.0
SIPM1003A-4R7M	4.70	24.0	10	7.0
SIPM1003A-8R2M	8.20	45.0	7.0	5.0
SIPM1003A-330M	33.00	160	4.0	2.6

- Notes

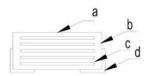
 1. All test data is referenced to 25 °C ambient
 2. Operating temperature range 55 °C to + 125 °C
 3. Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)
 4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
 5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions.

Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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(6)Structure and Components

Symbol	Components	Material
а	Marking	Ink (black)
b	Core	Alloy Spongy Powder
С	Wire	Polyamideimide copper wire
d	Terminal	Copper plated with Sn



(7)Reliability Tests

Mechanical Reliability									
No.	Test item	Performance	Test details						
1	Solderability	No case deformation or change in apperarance New solder coverage more than 95%	1.Preheat: 155℃±5℃, 60S±2S 2.Solder: lead-free. 3.Temperature: 240℃±5℃, flux 3.0S±0.5S.						
2	Mechanical shock	No case deformation or change in apperarance △L/Lo≦±10%	Acceleration: 100G Pulse time:: 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions						
3	Mechanical vibration	1.No case deformation or change in apperarance 2. △L/Lo ≦±10%	1. Reflow: 2times 2. Frequency: 10HZ~55HZ~10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm 4. Directions: X,Y,Z 5. Time: 12 cycle / direction						
	Reliability Test								
No.	Test item	Performance	Test details						
4	Thermal shock test	Inductance change: Within ± 10% Without distinct damage in appearance	First -55℃ for 30 minutes, last 125℃ for 30 minutes as 1 cycle. Go through 1000 cycles. Max transfer time is 3 minutes. Measured at room temperature after placing for 24±2 hours						
5	Humidity Resistance	Inductance change: Within ± 10% Without distinct damage in appearance	1.Reflow 2 times, 2.85℃,85%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours						
6	Low temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature: -55 ± 2°C 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours						
7	High temperature storage	Inductance change: Within ± 10% Without distinct damage in appearance	1. Temperature: +125 ± 2°C 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours						

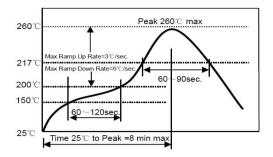
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Recommended Soldering Technologies (8)Soldering and Mounting 8-1,Re-flowing Profile

Preheat condition: 150 ~200 $^{\circ}\mathbb{C}/60$ ~120sec. Allowed time above 217 $^{\circ}\mathbb{C}$: 60~90sec.

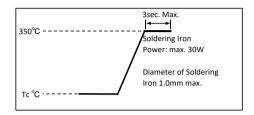
Max temp: 260 ℃

Max time at max temp: 10 sec. Solder paste: Sn/3.0Ag/0.5Cu Allowed Reflow time: 2x max

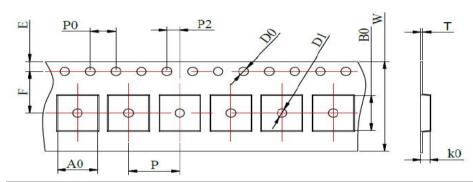


8-2, Iron Soldering Profile

Iron soldering power: Max. 30W Pre-heating: 150 ℃/60sec. Soldering time: 3sec. Max. Solder paste: Sn/3.0Ag/0.5Cu Max.1 times for iron soldering

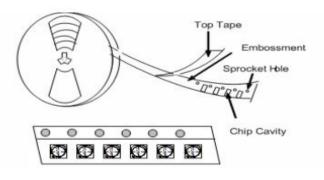


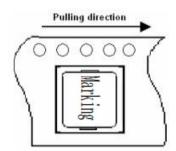
(9)Packaging Information 9-1,Tape Packaging Dimensions(Unit: mm)



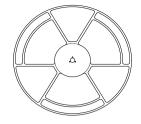
Туре		Tape Dimensions (mm)										
	W	Р	P0	P2	D0	D1	Т	A0	В0	K0	E	F
SIPM1003A	24±0.3	16±0.1	4±0.1	2±0.05	1.5±0.1	1.5±0.1	0.35±0.05	10.4±0.1	11.6±0.1	3.3±0.1	1.75±0.1	11.5±0.1

Taping Drawings (UNIT:mm)

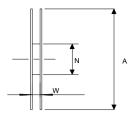




9-2,Reel Dimensions(Unit: mm)







Α	W	N	В	С
330+2.0	24±0.5	97±0.5	2.2+0.5	13.0±0.2

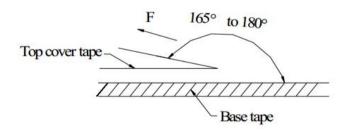
9-3,Packaging Quantity(PCS)

T. m. c	Standard Quantity					
Туре	Reel	Inner box	Carton box			
SIPM1003A	800 pcs / reel	2Reel / box (1600 pcs)	4 Middle boxes, (6400 pcs)			

9-4,Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N



Label

9-5,Reel Label

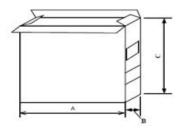
Label on the reel

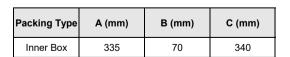
- ·Customer's part Number
- ·Lot Number
- ·Quantity
- ·Date code

Shipping Label

- ·Customer's part Number
- ·Manufacturer's part Number
- ·Quantity
- ·Date code

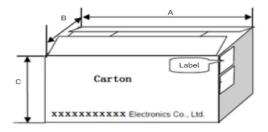
9-6,Inner Box





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9-7,Carton



Packing Type	A (mm)	B (mm)	C (mm)
Туре	360	360	360

(10)Note

·Storage Conditions

To maintain the solderability of terminal electrodes:

- 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature: 5 to 30deg.C, Humidity: 75% Max.
- Recommended products should be used within 24 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.